PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wen-Kun Yang	12/31/2007
Wen-Pin Yang	12/31/2007

RECEIVING PARTY DATA

Name:	Advanced Chip Engineering Technology Inc.
Street Address:	No. 65, Guangfu N. Rd.
Internal Address:	Hukou Township
City:	Hsinchu County
State/Country:	TAIWAN
Postal Code:	303

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11945723

OP $40.00 11945723

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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ATTORNEY DOCKET NUMBER:	HK9013US.2
NAME OF SUBMITTER:	Michael A. Jaffe

Total Attachments: 2
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Practitioner's Docket No. HK9013US.2

PATENT

For: U.S. Rights
For: U.S. Application
By: Inventor

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNORS of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNORS:

Wen-Kun YANG
47, Lane 6, An-Kang St.
Hsin-Chu City
Taiwan R.O.C
Nationality: Taiwan, R.O.C.

Wen-Pin YANG
No. 112, Jhulian St.
Hsinchu City 300
Taiwan, R.O.C.
Nationality: Taiwan, R.O.C.

hereby sell, assign and transfer to

ASSIGNEE:

Advanced Chip Engineering Technology Inc.
No. 65, Guangfu N. Rd.
Hukou Township
Hsinchu County 303, Taiwan, R.O.C.

Country of Formation: Taiwan, R.O.C.

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to any and all improvements which are disclosed in the invention entitled:

STRUCTURE OF IMAGE SENSOR MODULE AND METHOD FOR MANUFACTURING OF WAFER LEVEL PACKAGE

and which is found in (37 C.F.R. Section 3.21) and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNORS hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNORS further covenant that ASSIGNEE will, upon their request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNORS and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or their legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal on the date(s) set forth below.

Date: Dec. 31, 2007

Signature of Wen-Kun YANG

Date: Dec. 31, 2007

W. P. Yang

Signature of Wen-Pin YANG